

**Product Summary**

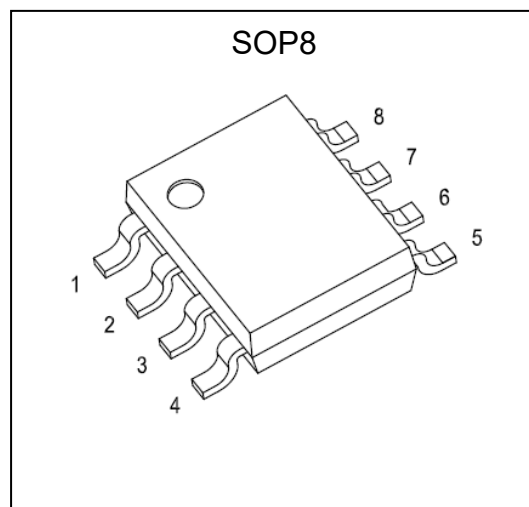
$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
60V	9mΩ@10V	12A
	13mΩ@4.5V	

**Feature**

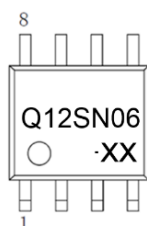
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Optimized for fast-switching applications

**Application**

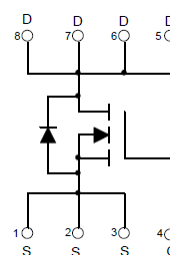
- Synchronous Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive application



**MARKING:**



**Equivalent Circuit**



**ABSOLUTE MAXIMUM RATINGS ( $T_J=25^{\circ}C$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Continuous Drain Current <sup>G</sup>	$I_D$	$T_C=25^{\circ}C$	12
		$T_C=100^{\circ}C$	9
Drain to Source Voltage	$V_{DS}$	60	V
Gate to Source Voltage	$V_{GS}$	±20	V
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	48	A
Avalanche Energy <sup>C</sup>	$E_{AS}$	195	mJ
Power Dissipation <sup>A</sup>	$P_D$	$T_C=25^{\circ}C$	3.1
		$T_C=100^{\circ}C$	2.0
Thermal Resistance Junction to Ambient <sup>A</sup>	$R_{\theta JA}$	$T \leq 10s$	40
Thermal Resistance Junction to Ambient <sup>A,D</sup>		Steady-State	75
Thermal Resistance Junction to Case	$R_{\theta JC}$	24	$^{\circ}C/W$
Operating and Storage Temperature	$T_J, T_{stg}$	-55 ~ 150	$^{\circ}C$

**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	60			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> = 0V, T <sub>J</sub> =25°C			1	μA
		V <sub>DS</sub> =60V, V <sub>GS</sub> = 0V, T <sub>J</sub> =100°C			100	
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.1	1.7	2.5	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =12A		8.2	9.0	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A		10.5	13.0	mΩ
Forward tranconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =12A		70		S
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> Open, f=1MHz		1.6		Ω
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f =1MHz		1988		pF
Output Capacitance	C <sub>oss</sub>			470		
Reverse Transfer Capacitance	C <sub>rss</sub>			14		
Total gate charge(10V)	Q <sub>g</sub>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =12A		31		nC
Gate-source charge	Q <sub>gs</sub>			6		
Gate-drain charge	Q <sub>gd</sub>			5		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =2.5Ω, R <sub>GEN</sub> =3Ω		10.5		ns
Turn-on rise time	t <sub>r</sub>			4.5		
Turn-off delay time	t <sub>d(off)</sub>			29.5		
Turn-off fall time	t <sub>f</sub>			8		
<b>Source-Drain Diode characteristics</b>						
Body Diode Voltage	V <sub>DS</sub>	T <sub>J</sub> =25°C, I <sub>S</sub> =12A, V <sub>GS</sub> = 0V		0.9	1.2	V
Body-Diode Continuous Current <sup>G</sup>	I <sub>S</sub>				12	A
Reverse Recovey Time	t <sub>rr</sub>	I <sub>F</sub> =12A, dI/dt=500A/μs		17		ns
Reverse Recovey Charge	Q <sub>rr</sub>				58	

A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25°C. The Power dissipation P<sub>D</sub> is based on R<sub>θJA</sub> ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.

D. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to case R<sub>θJC</sub> and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150°C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

**Typical Electrical and Thermal Characteristics**

Fig 1: Output Characteristics

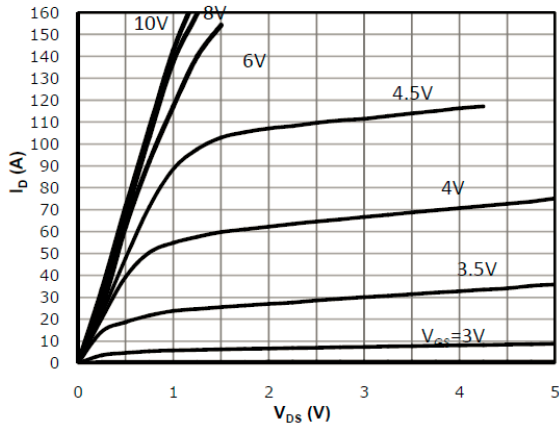


Fig 2: Transfer Characteristics

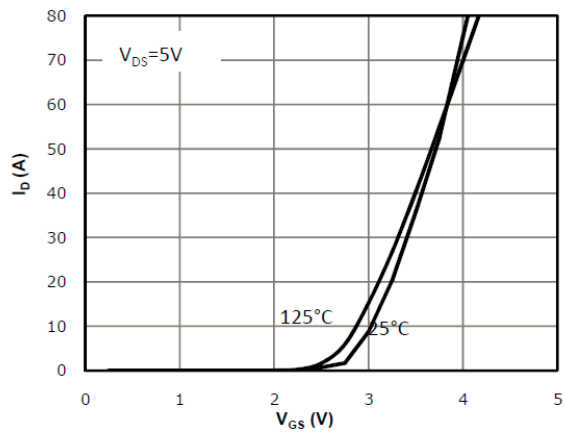


Fig 3: Rds(on) vs Drain Current and Gate Voltage

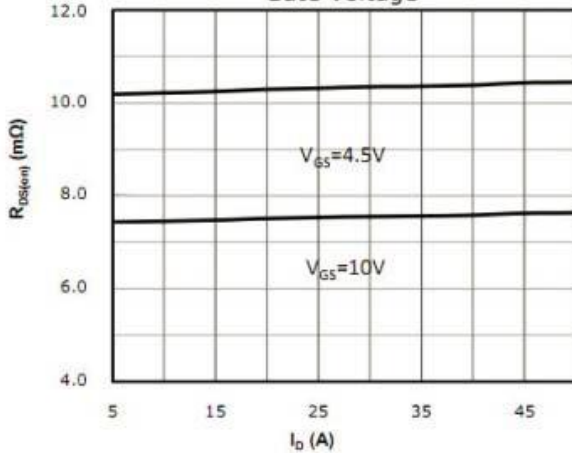


Fig 4: Rds(on) vs Gate Voltage

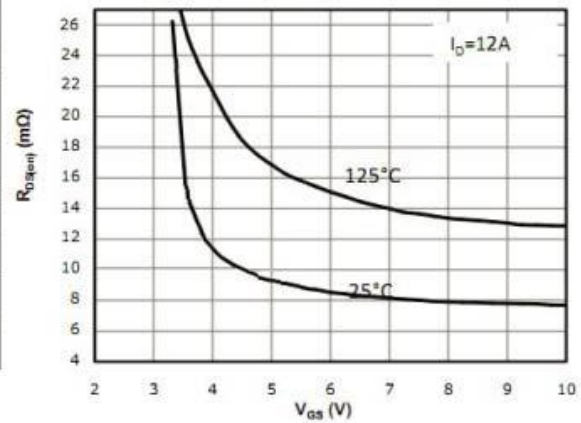


Fig 5: Rds(on) vs. Temperature

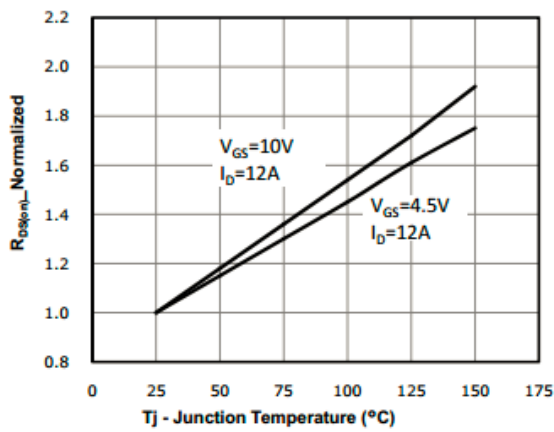


Fig 6: Capacitance Characteristics

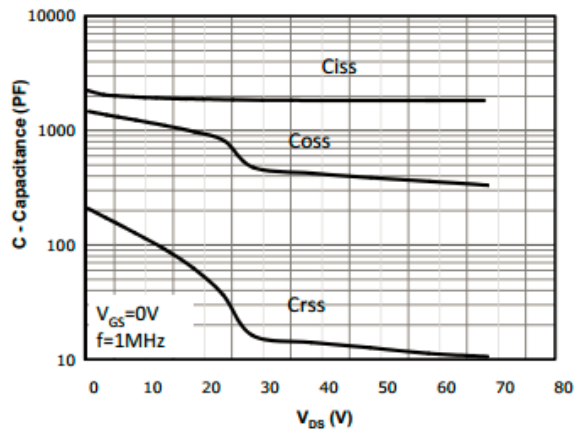


Fig 7: Gate Charge Characteristics

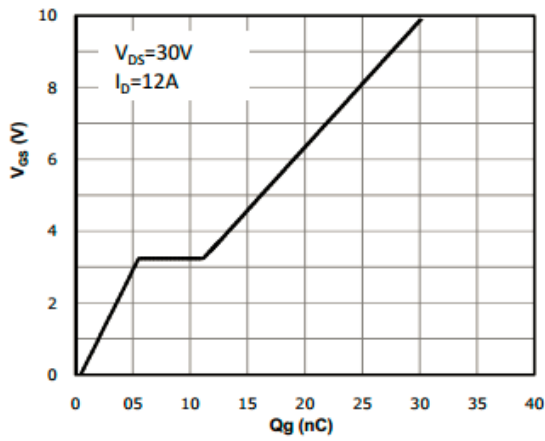


Fig 8: Body-diode Forward Characteristics

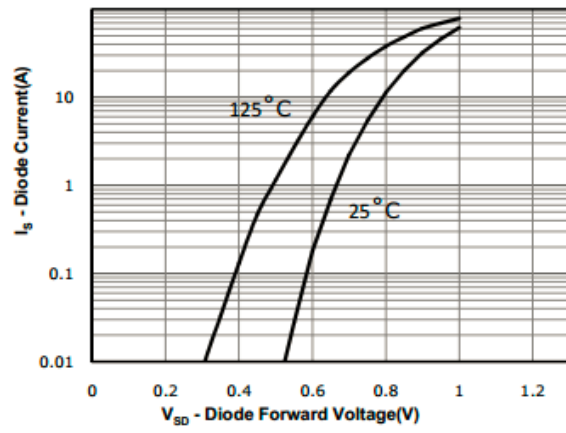


Fig 9: Power Dissipation

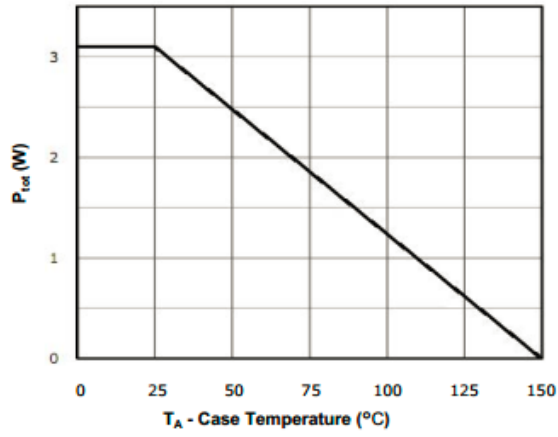
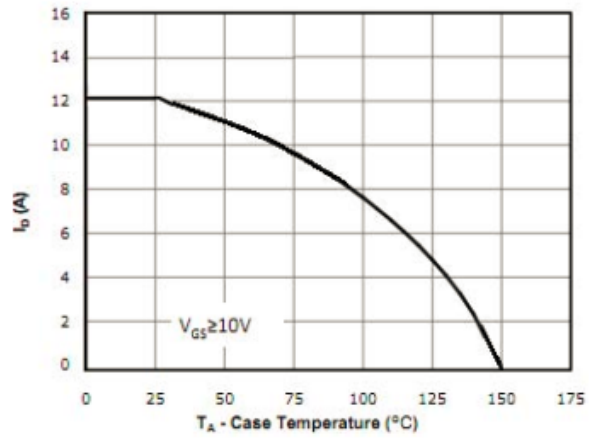
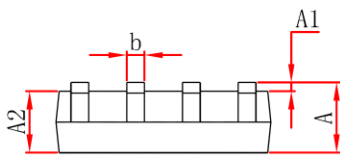
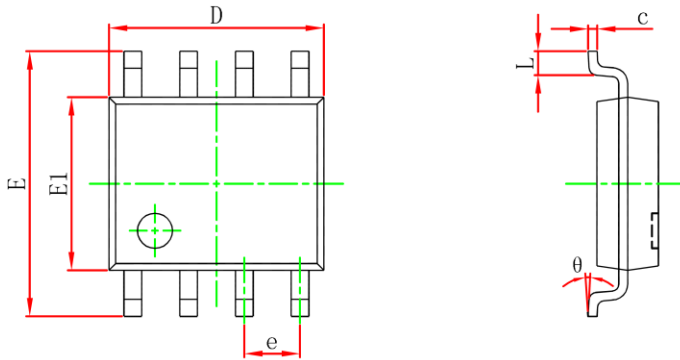


Fig 10: Drain Current Derating



## SOP8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

单击下面可查看定价，库存，交付和生命周期等信息

[>>GP\(格瑞宝\)](#)